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1. Name of conveying party(ies)

Jae Suk LEE

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) 05-10-2005

- Assignment Merger
- Security Agreement Change of Name
- Joint Research Agreement
- Government Interest Assignment
- Executive Order 9424, Confirmatory License
- Other

2. Name and address of receiving party(ies)

Name: DongbuAnam Semiconductor Inc.

Internal Address:

Street Address: 891-10, Daechi-dong, Kangnam-gu

City: Seoul

State:

Country: KOREA Zip: 135-280

Additional name(s) & address(es) attached? Yes No

4. Application or patent number(s):

This document is being filed together with a new application.

A. Patent Application No.(s)

B. Patent No.(s)

05/13/2005 EAYALEW1 00000021 11126900

40.00 DP

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Andrew D. Fortney, Ph.D.

Internal Address: The Law Offices of Andrew D. Fortney, Ph.D., P.C.

Street Address: 7257 N. Maple Ave., Suite 107

City: Fresno

State: CA Zip: 93720

Phone Number: 559-299-0128

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Email Address: drew@fortneylaw.com

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.

- Authorized to be charged by credit card
- Authorized to be charged to deposit account
- Enclosed
- None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers 1447
Expiration Date 02/08

b. Deposit Account Number

Authorized User Name

9. Signature:

05-10-2005

Signature

Date

Andrew D. Fortney, Ph.D.

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

2

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Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

Attorney Docket No.: PPW05-004DS

ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, the undersigned,
Jae Suk LEE

who have created a certain invention for which an application for United States Letters Patent was executed by me concurrently herewith and entitled:

Method of Forming Pre-Metal Dielectric Layer

Do hereby sell, assign and transfer to DongbuAnam Semiconductor Inc., a corporation of Republic of Korea, having a place of business at 891-10, Daechi-dong, Kangnam-gu, Seoul, 135-280, its successors, assigns, and legal representatives, the full and exclusive right to said invention and said application and to any and all inventions described in said application for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties;

Agree that DongbuAnam Semiconductor Inc., hereinafter referred to as Assignee, may apply for and receive Letters Patent for said invention and said inventions, hereinafter referred to as said invention, in its own name, in the United States, its territorial possessions, and all foreign countries; and that, when requested to carry out in good faith the intent and purpose of this assignment, at the expense of said Assignee, its successors, assigns and legal representatives, the undersigned will execute all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, execute all rightful oaths, assignments, powers of attorney and other papers, testify in any legal or quasi legal proceedings; communicate to said Assignee, its successors, assigns or legal representatives all facts known to the undersigned relating to said invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or legal representatives shall consider desirable for aiding in securing, maintaining and enforcing proper patent protection for said invention and for vesting title to said invention and all applications for patents on said invention in said Assignee, its successors, assigns, or legal representatives; and

Covenant with said Assignee, its successors, assigns, or legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

IN TESTIMONY WHEREOF I have hereunto set MY signature on the date indicated below.

Full Name of Sole/First Inventor:	
Jae Suk LEE	
Inventor's Signature:	Date: Month/Day/Year
<i>Jae Suk Lee</i>	5/10/2005

Full Name of Second Inventor, if any:	
Inventor's Signature:	Date: Month/Day/Year

Customer No. 36872